

Initial Product/Process Change Notification Document #: IPCN22454X1

Issue Date: 1 February 2019

| Title of Change: | PCN Update Notice - Cancellation of IPCN22454X. | | | |
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| Proposed First Ship date: | 1 February 2019 | | | |
| Contact Information: | Contact your local ON Semiconductor Sales Office or < <u>wirasa.nontharith@onsemi.com</u> > | | | |
| Samples: | Contact your local ON Semiconductor Sales Office or < PCN.Samples@onsemi.com Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. | | | |
| Type of Notification: | This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are typically issued 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < < PCN.Support@onsemi.com > | | | |
| Change Part Identification: | Date code will identify unit with this change. | | | |
| Change Category: | Wafer Fab Change ✓ Assembly Change Test Change Other | | | |
| Change Sub-Category(s): ☐ Manufacturing Site Addition ☐ Manufacturing Site Transfer ☐ Manufacturing Process Change | | □ Datasheet/Product Doc change□ Shipping/Packaging/Marking□ Other: | | |
| Sites Affected: | ON Semiconductor Sites: NONE | External Foundry/Subcon Sites: Sub-con Thailand | | |
| Description and Purpose: | | | | |
| This Update Notice announces to customers the cancellation of IPCN22454X due to removal of affected OPNs (Orderable Part Number) from the List of Affected Parts, selection of new Qualification Vehicles and run Reliabity again. | | | | |
| IPCN22454X previously announced its customers the qualification of Sub-con Thailand for the assembly changing the Die Attach Material from Epoxy Dispense (QMI519) to CDAF215. This is to improve the epoxy fillet height to meet customer requirement and also improve DA quality at assembly process (no epoxy overflow, bridging, filletheight out, epoxy on die, epoxy on lead, epoxy void). | | | | |
| | Before Change Description | After Change Description | | |
| Die Attac | ch Epoxy Dispense (QMI519) | CDAF215 | | |
| There is no product marking change as a result of this change. | | | | |

TEM001790 Rev. A Page 1 of 2



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Qualification Plan:

QV DEVICE NAME: 74LVTH125MX

RMS: 042578

PACKAGE: F456 | SOIC14

| Test | Specification | Condition | Interval |
|---------|---------------------|-------------------------------|----------|
| HTOL | JESD22-A108 | Ta=145°C, 100 % max rated Vcc | 504 hrs |
| PC | J-STD-020 JESD-A113 | MSL 1 @ 260 °C | |
| HAST-PC | JESD22-A110 | 130°C, 85% RH, 18.8psig, bias | 96 hrs |

List of Affected Parts:

| Part Number | Qualification Vehicle |
|-------------|-------------------------------------------------------------------|
| 74LVTH125MX | 74LVTH125MX (QV1 Big die size) MM74HC08MX (QV2 Small die size) |
| MM74HC164MX | |
| 74LCX00MX | |
| 74LCX08MX | |
| 74LCX125MX | |
| 74LCX07MX | |
| 74ACT04SCX | |
| 74VHC04MX | |
| 74VHC14MX | |
| MM74HC125MX | |
| MM74HC02MX | |
| 74VHC00MX | |
| MM74HC08MX | |
| MM74HC32MX | |
| 74VHCT08AMX | |

TEM001790 Rev. A Page 2 of 2